

Resin	Product Description	Tg (°C)	Z Axis Expansion (%)	UL-94 Rating	Td 5% (°C)	H ₂ O Absorp (%)	Tc (W/m-k)	IPC4101 Class	Comments
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Polyimide Products

33N	Flame Retardant Polyimide	250	1.2	V0	389	0.21	0.20	GIL/40/41	Max Flame Retardance
35N	Flame Retardant Polyimide	250	1.2	V1	407	0.26	0.20	GIL/40/41	Reduced Cure Time
HF-50	Powdered Poly Hole Fill Compound	250	0.55	N/A	>400	0.40	0.50	N/A	Hole/Via Fill Compound
84N	Filled Polyimide Prepreg	250	1.0	Meets HB	407	0.30	0.25	GIL/40/41	For Via/Clearance Hole Filling
85N	High Temp Polyimide	250	1.2	HB	407	0.27	0.20	GIL/40/41	Optimum Long Term Stability
85HP	High Performance Polyimide	>250	≤1.0	Meets HB	430	0.19	0.50	GIL/40/41/43	Tc (W/mK) is 2x Polyimide
84HP	Filled Polyimide Prepreg	>250	≤1.0	Meets HB	430	0.19	0.50	GIL/40/41/43	Fills Thick Copper Layers
86HP	High Performance Polyimide	>250	≤1.0	V0	430	0.12	0.60	GIL/40/41/43	

Low Flow Products

37N	Low Flow Polyimide Prepreg	200	2.3	Meets V0	340	<1.00	0.30	GIJ/42	Rigid Flex Applications
38N	2nd Gen Low Flow Polyimide Prepreg	200	1.5	Meets V0	330	<1.00	0.30	GIJ/42	Enhanced Rheology Rigid Flex
47N	Modified Epoxy Low Flow	135	3.5	V0	315	0.10	0.25	GFG/21	Heat Sink Bond, Low Temp Cure
49N	Multifunctional Epoxy Low Flow	170	3.1	V0	303	0.10	0.25	GFG/26	Rigid-Flex, Heat Sinks
51N	Lead-Free Epoxy Low Flow	170	2.6	V0	368	0.15	0.25	GFG/126	Lead-Free Solderable, Rigid-Flex

Epoxy Products

44N	Filled Epoxy Prepreg	170	2.2	V0	>300	0.10	0.30	GFG/98	For Via/Clearance Hole Fill
45N	Multifunctional Epoxy	175	2.4	V0	>300	0.10	0.25	GFG/26	For Via/Clearance Hole Fill

Controlled Thermal Expansion/SMT

45NK	Woven Aramid Reinforced Epoxy	170	2.8	V0	>300	0.80	0.22	AFN/50	Kevlar® X-Y CTE of 5-7 ppm/°C
55NT	Epoxy Nonwoven Aramid	170	3.5	V0	368	0.30	0.20	BFG/55	X-Y CTE of 6-9 ppm/°C
85NT	Polyimide Nonwoven Aramid	250	2.3	Meets HB	426	0.60	0.20	BIL/53	X-Y CTE of 7-9 ppm/°C

Additional Product Information

- Reverse Treated and Double Treated Foils are available upon request
- Thin copper foils are available for ultra fine-line applications
- All products are manufactured using E-Type Fiberglass unless otherwise specified

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